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Understanding Embedded - FPGAs (Field Programmable Gate Array)

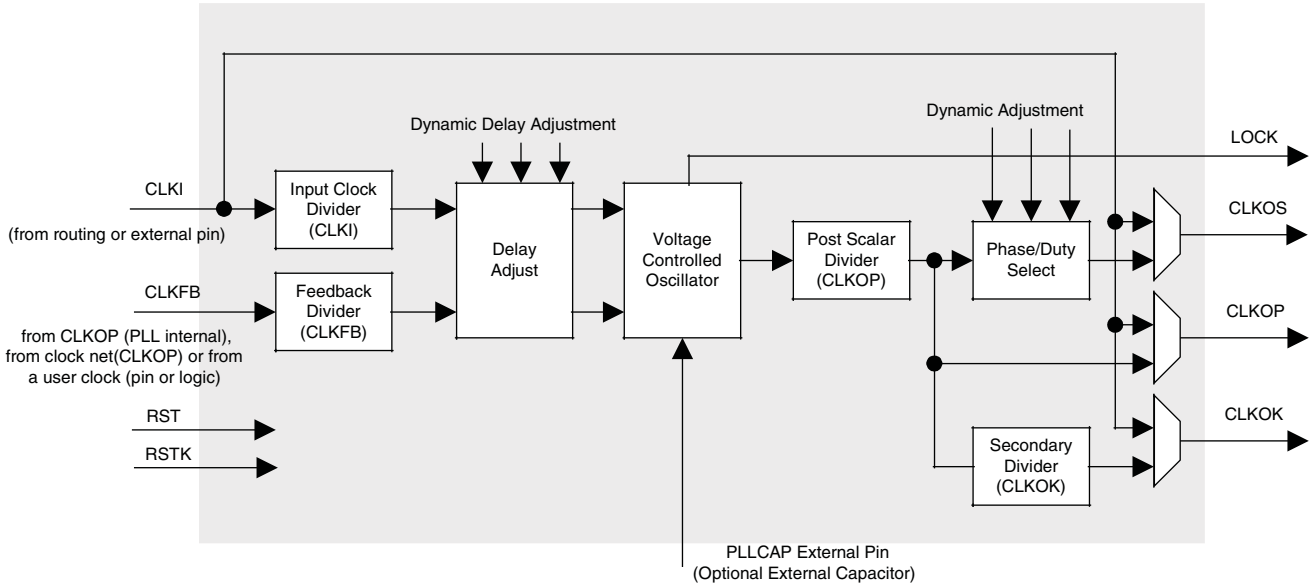
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	1500
Number of Logic Elements/Cells	12000
Total RAM Bits	226304
Number of I/O	131
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-12se-5q208i

Figure 2-5. General Purpose PLL (GPLL) Diagram



Standard PLL (SPLL)

Some of the larger devices have two to six Standard PLLs (SPLLs). SPLLs have the same features as GPLLs but without delay adjustment capability. SPLLs also provide different parametric specifications. For more information, please see the list of additional technical documentation at the end of this data sheet.

Table 2-4 provides a description of the signals in the GPLL and SPLL blocks.

Table 2-4. GPLL and SPLL Blocks Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from CLKOP (PLL internal), from clock net (CLKOP) or from a user clock (PIN or logic)
RST	I	"1" to reset PLL counters, VCO, charge pumps and M-dividers
RSTK	I	"1" to reset K-divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (no phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	"1" indicates PLL LOCK to CLKI
DDAMODE[1]	I	Dynamic Delay Enable. "1": Pin control (dynamic), "0": Fuse Control (static)
DDAIZR[1]	I	Dynamic Delay Zero. "1": delay = 0, "0": delay = on
DDAILAG[1]	I	Dynamic Delay Lag/Lead. "1": Lead, "0": Lag
DDAIDEL[2:0][1]	I	Dynamic Delay Input
DPA MODES	I	DPA (Dynamic Phase Adjust/Duty Cycle Select) mode
DPHASE [3:0]	I	DPA Phase Adjust inputs
DDDUTY [3:0]	—	DPA Duty Cycle Select inputs

1. These signals are not available in SPLL.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becomes active.

These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

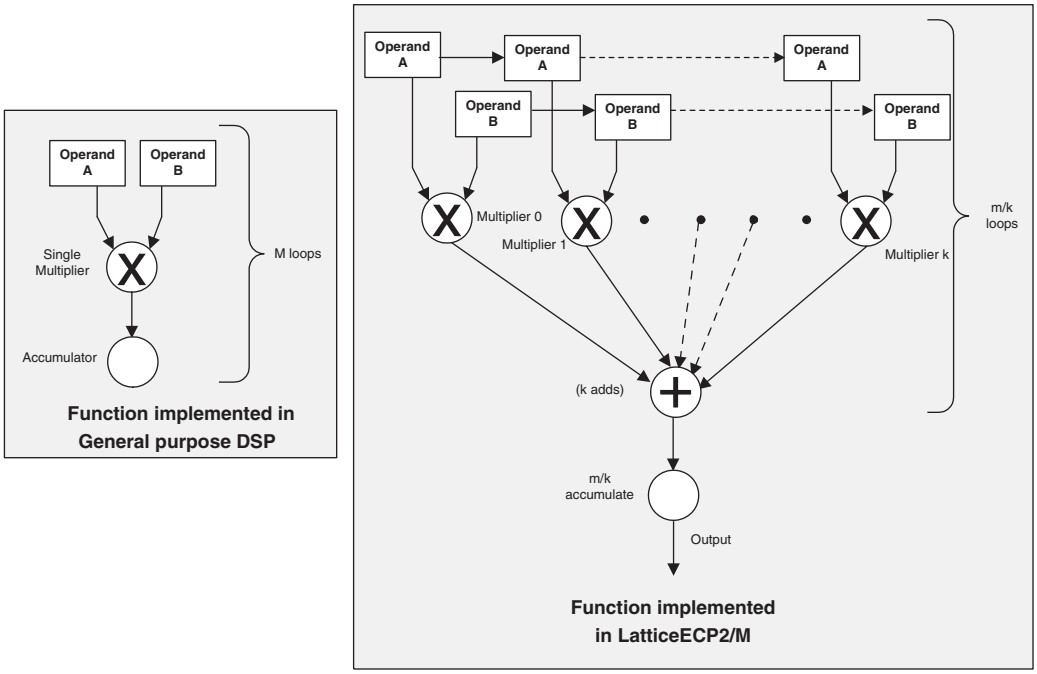
sysDSP™ Block

The LatticeECP2/M family provides a sysDSP block, making it ideally suited for low cost, high performance Digital Signal Processing (DSP) applications. Typical functions used in these applications are Finite Impulse Response (FIR) filters, Fast Fourier Transforms (FFT) functions, Correlators, Reed-Solomon/Turbo/Convolution encoders and decoders. These complex signal processing functions use similar building blocks such as multiply-adders and multiply-accumulators.

sysDSP Block Approach Compared to General DSP

Conventional general-purpose DSP chips typically contain one to four (Multiply and Accumulate) MAC units with fixed data-width multipliers; this leads to limited parallelism and limited throughput. Their throughput is increased by higher clock speeds. The LatticeECP2/M, on the other hand, has many DSP blocks that support different data-widths. This allows the designer to use highly parallel implementations of DSP functions. The designer can optimize the DSP performance vs. area by choosing an appropriate level of parallelism. Figure 2-22 compares the fully serial and the mixed parallel and serial implementations.

Figure 2-22. Comparison of General DSP and LatticeECP2/M Approaches



sysDSP Block Capabilities

The sysDSP block in the LatticeECP2/M family supports four functional elements in three 9, 18 and 36 data path widths. The user selects a function element for a DSP block and then selects the width and type (signed/unsigned) of its operands. The operands in the LatticeECP2/M family sysDSP Blocks can be either signed or unsigned but not mixed within a function element. Similarly, the operand widths cannot be mixed within a block. In the LatticeECP2/M family the DSP elements can be concatenated.

The resources in each sysDSP block can be configured to support the following elements:

- MULT (Multiply)
- MAC (Multiply, Accumulate)
- MULTADDSUB (Multiply, Addition/Subtraction)
- MULTADDSUBSUM (Multiply, Addition/Subtraction, Accumulate)

The number of elements available on each block depends in the width selected from the three available options x9, x18, and x36. A number of these elements are concatenated for highly parallel implementations of DSP functions. Table 2-7 shows the capabilities of the block.

Table 2-7. Maximum Number of Elements in a Block

Width of Multiply	x9	x18	x36
MULT	8	4	1
MAC	2	2	—
MULTADDSUB	4	2	—
MULTADDSUBSUM	2	1	—

Some options are available in four elements. The input register in all the elements can be directly loaded or can be loaded as a shift register from previous operand registers. By selecting “dynamic operation” the following operations are possible:

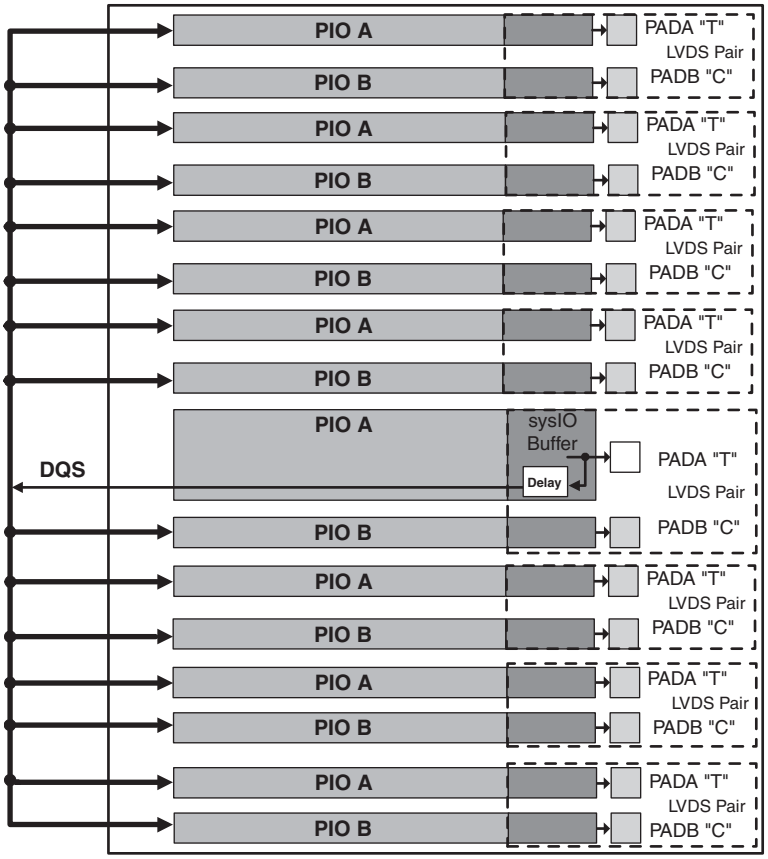
- In the ‘Signed/Unsigned’ options the operands can be switched between signed and unsigned on every cycle.
- In the ‘Add/Sub’ option the Accumulator can be switched between addition and subtraction on every cycle.
- The loading of operands can switch between parallel and serial operations.

Top Edge

The PICs on the top edge are different from PIOs on the left, right and bottom edges. PIOs on this edge do not have DDR registers or DQS signals.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table. The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. Interfaces on the left and right edges are designed for DDR memories that support 16 bits of data, whereas interfaces on the bottom are designed for memories that support 18 bits of data.

Figure 2-33. DQS Input Routing for the Left and Right Edges of the Device



O standards (together with their supply and reference voltages) supported by LatticeECP2/M devices. For further information about utilizing the sysI/O buffer to support a variety of standards please see the the list of additional technical information at the end of this data sheet.

Table 2-13. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVCMOS33	—	—
LVCMOS25	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12	—	—
PCI 33	—	3.3
HSTL18 Class I, II	0.9	—
HSTL15 Class I	0.75	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I, II	0.9	—
Differential Interfaces		
Differential SSTL18 Class I, II	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I	—	—
Differential HSTL18 Class I, II	—	—
LVDS, MLVDS, LVPECL, BLVDS, RSDS	—	—

1 When not specified, V_{CCIO} can be set anywhere in the valid operating range (page 3-1).

Symbol	Parameter	Min.	Max.	Units
V_{CCP}[6]	PLL and Reference Clock Buffer Power	1.14	1.26	V

1. If V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC}. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX}. V_{CCPLL} must be connected to the same power supply as V_{CC} through careful filtering and decoupling.
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CCAUX} ramp rate must not exceed 30mV/µs during power-up when transitioning between 0V and 3.3V.
4. For proper power-up configuration, users must ensure that the configuration control signals such as the CFGx, INITN, PROGRAMN and DONE pins are driven to the proper logic levels when the device powers up. The device power-up is triggered by the last of V_{CC}, V_{CCAUX} or V_{CCIO8} supplies that reaches its minimum valid levels. Alternatively, if the configuration control signals are pulled up by V_{CCIO8}, the V_{CCIO8} (configuration I/O bank) voltage must be powered up prior to or at the same time as the last of VCC or VCCAUX reaches its minimum levels.
5. For power-up, V_{CC} must reach its valid minimum value before powering up V_{CCAUX} (LatticeECP2/M “S” version devices only).
6. V_{CCRX},V_{CCTX} and V_{CCP} must be tied together in each quad and all quads need to be powered up.
7. For more power supply design recommendations, refer to TN1114 Electrical Recommendations for Lattice SERDES.

Hot Socketing Specifications[1, 2, 3, 4]

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O leakage current	$0 \le V_{IN} \le V_{IH}$ (MAX.)	—	—	+/-1000	µA
I_{HDIN}[5]	SERDES average input current when device is powered down and inputs are driven		—	—	4	mA

1. V_{CC}, V_{CCAUX} and V_{CCIO} should rise/fall monotonically. V_{CC} and V_{CCPLL} must be connected to the same power supply (applies to ECP2-6, ECP2-12 and ECP2-20 only).
2. $0 \le V_{CC} \le V_{CC}$ (MAX), $0 \le V_{CCIO} \le V_{CCIO}$ (MAX) or $0 \le V_{CCAUX} \le V_{CCAUX}$ (MAX).
3. I_{DK} is additive to I_{PU}, I_{PW} or I_{BH}.
4. LVCMOS and LVTTL only.
5. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed V_{CCIB} of 1.575V, 8b10b data and internal AC coupling.

ESD Performance

Please refer to LatticeECP2/M Product Family Qualification Summary for complete qualification data, including ESD performance.

SERDES External Reference Clock (LatticeECP2M Family Only)

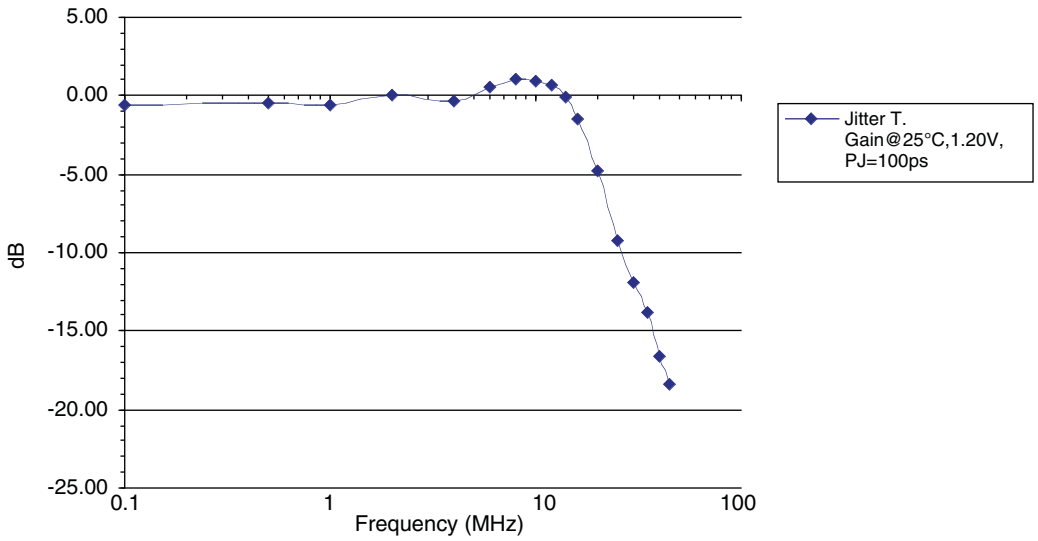
The external reference clock selection and its interface are a critical part of system applications for this product. Table 3-14 specifies reference clock requirements, over the full range of operating conditions.

Table 3-14. External Reference Clock Specification (refclkp/refclkn)

Symbol	Description	Min.	Typ.	Max.	Units
F_{REF}	Frequency range	25	—	320	MHz
$F_{REF-PPM}$	Frequency tolerance	-300	—	300	ppm
$V_{REF-IN-SE}$	Input swing, single-ended clock[1]	100	—	1200	mV, p-p
V_{REF-IN}	Input levels	0	—	V_{CCP} + 0.8	V
$V_{REF-CM-DC}$	Input common mode range (DC coupled)	0.5	—	1.2	V
$V_{REF-CM-AC}$	Input common mode range (AC coupled)[2]	0	—	1.5	V
D_{REF}	Duty cycle[3]	40	—	60	%
T_{REF-R}	Rise time (20% to 80%)		500	1000	ps
T_{REF-F}	Fall time (80% to 20%)		500	1000	ps
$Z_{REF-IN-TERM}$	Input termination		50/2K		Ohms
$C_{REF-IN-CAP}$	Input capacitance[4]	—	—	1.5	pF

1. The signal swing for a single-ended input clock must be as large as the p-p differential swing of a differential input clock to get the same gain at the input receiver. Lower swings for the clock may be possible, but will tend to increase jitter.
2. When AC coupled, the input common mode range is determined by:
(Min input level) + (Peak-to-peak input swing)/2 ≤ (Input common mode voltage) ≤ (Max input level) - (Peak-to-peak input swing)/2
3. Measured at 50% amplitude.
4. Input capacitance of 1.5pF is total capacitance, including both device and package.

Figure 3-13. Jitter Transfer



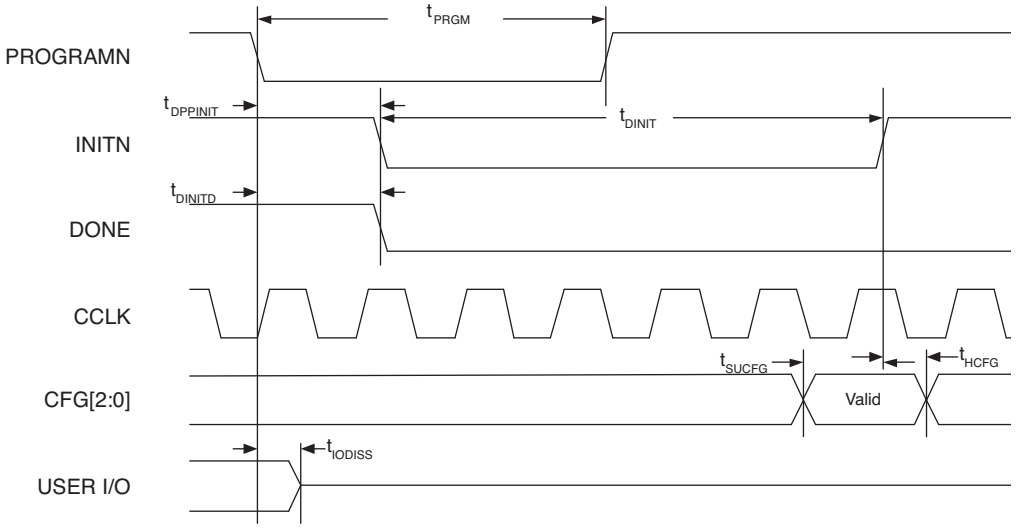
Note: This graph is for a nominal device.

SERDES Power-Down/Power-Up Specification

Table 3-15. Power-Down and Power-Up Specification

Symbol	Description	Max.	Units
t_{PWRDN}	Power-down time after all power down register bits set to '0'	10	µs
t_{PWRUP}	Power-up time after all power down register bits set to '1'	100	µs

Figure 3-18. Configuration from PROGRAMN Timing



1. The CFG pins are normally static (hard wired)

Figure 3-19. Wake-Up Timing

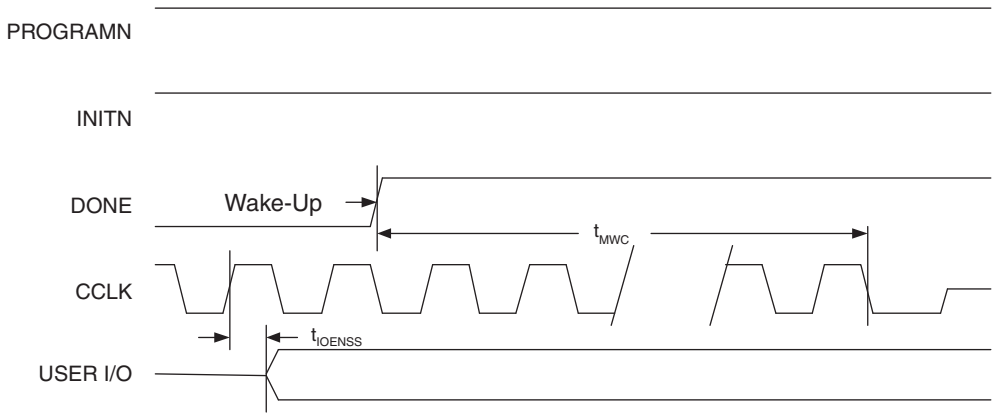
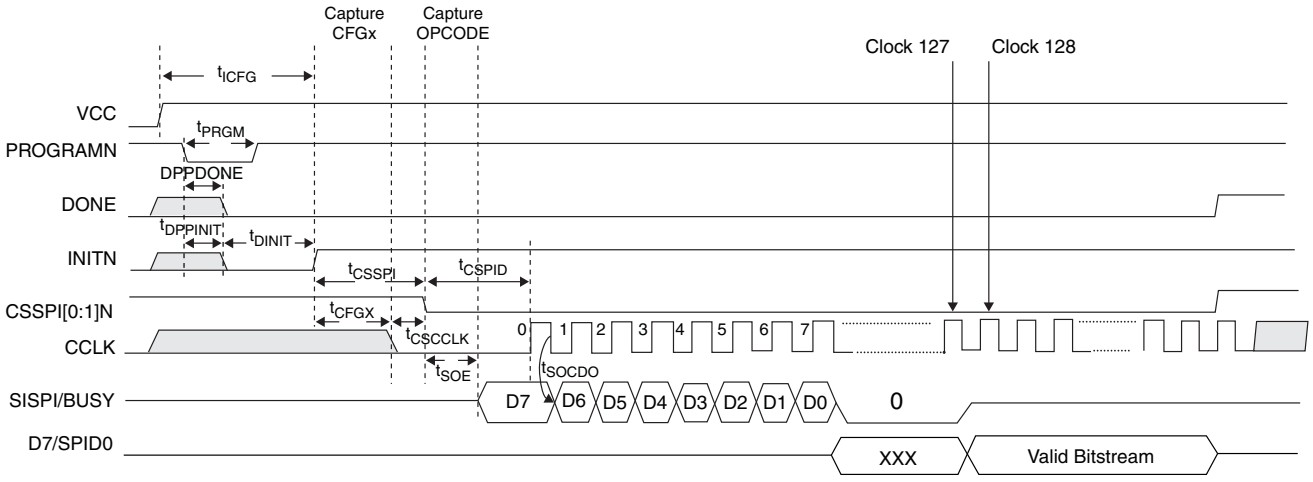


Figure 3-20. SPI/SPIm Configuration Waveforms



LatticeECP2 Pin Information Summary, LFE2-6 and LFE2-12

Pin Type		LFE2-6		LFE2-12			
		144 TQFP	256 fpBGA	144 TQFP	208 PQFP	256 fpBGA	484 fpBGA
Single Ended User I/O		90	190	93	131	193	297
Differential Pair User I/O		43	95	45	62	96	148
Configuration	TAP Pins	5	5	5	5	5	5
	Muxed Pins	14	14	14	14	14	14
	Dedicated Pins (Non TAP)	7	7	7	7	7	7
Non Configuration	Muxed Pins	34	54	33	40	54	57
	Dedicated Pins	3	3	3	3	3	3
VCC		10	7	10	14	7	16
VCCAUX		4	4	4	8	4	16
VCCPLL		0	0	0	0	0	0
VCCIO	Bank0	1	2	1	2	2	4
	Bank1	1	2	1	2	2	4
	Bank2	1	2	1	2	2	4
	Bank3	1	2	1	2	2	4
	Bank4	1	2	1	2	2	4
	Bank5	1	2	1	2	2	4
	Bank6	1	2	1	2	2	4
	Bank7	1	2	1	2	2	4
	Bank8	1	1	1	2	1	2
GND, GND0 to GND7		12	20	12	22	20	60
NC		4	3	1	0	0	44
Single Ended/ Differential I/O Pairs per Bank (including emulated with resistors)	Bank0	8/4	18/6	8/4	18/9	18/9	50/25
	Bank1	17/8	34/17	18/9	18/9	34/17	46/23
	Bank2	4/2	20/10	4/2	11/5	20/10	24/12
	Bank3	8/4	12/6	8/4	11/5	12/6	16/8
	Bank4	18/9	32/16	18/9	19/9	32/16	46/23
	Bank5	8/4	14/7	10/5	18/9	17/8	46/23
	Bank6	9/4	26/13	9/4	18/8	26/13	32/16
	Bank7	12/6	20/10	12/6	12/6	20/10	23/11
	Bank8	6/2	14/7	6/2	6/2	14/7	14/7
True LVDS I/O Pairs per Bank	Bank0 (Top Edge)	0	0	0	0	0	0
	Bank1 (Top Edge)	0	0	0	0	0	0
	Bank2 (Right Edge)	1	5	1	4	5	6
	Bank3 (Right Edge)	3	3	3	3	3	4
	Bank4 (Bottom Edge)	0	0	0	0	0	0
	Bank5 (Bottom Edge)	0	0	0	0	0	0
	Bank6 (Left Edge)	2	7	2	6	7	8
	Bank7 (Left Edge)	5	5	5	5	5	5
	Bank8 (Right Edge)	0	0	0	0	0	0

LatticeECP2M Power Supply and NC (Cont.)

Signal	1152 fpBGA
V_{CC}	AA13, AA14, AA15, AA16, AA17, AA18, AA19, AA20, AA21, AA22, AB14, AB15, AB20, AB21, N14, N15, N20, N21, P13, P14, P15, P16, P17, P18, P19, P20, P21, P22, R13, R14, R21, R22, T14, T21, U14, U21, V14, V21, W14, W21, Y13, Y14, Y21, Y22
V_{CCIO0}	C12, C16, E14, H12, H16, M14, M15
V_{CCIO1}	C19, C23, E21, H19, H23, M20, M21
V_{CCIO2}	G32, K28, K32, N27, N32, P23, R23, T27, T32
V_{CCIO3}	AA23, AB27, AB32, AE28, AE32, AH32, W27, W32, Y23
V_{CCIO4}	AC20, AC21, AG19, AG23, AK21, AM19, AM23
V_{CCIO5}	AC14, AC15, AG12, AG16, AK14, AM12, AM16
V_{CCIO6}	AA12, AB3, AB8, AE3, AE7, AH3, W3, W8, Y12
V_{CCIO7}	G3, K3, K7, N3, N8, P12, R12, T3, T8
V_{CCIO8}	AD28, AG32
V_{CCJ}	AK3
V_{CCAUX}	AB12, AB13, AB22, AB23, AC13, AC22, M13, M22, N12, N13, N22, N23
V_{CCPLL}	R15, R20, Y15, Y20
SERDES Power[3]	D7, B9, B8, D9, B7, E7, B6, D8, E6, D6, D4, B5, D3, B4, C1, B3, B1, B2, B33, B34, B32, C34, B31, D32, B30, D31, E29, D29, D27, B29, E28, B28, D26, B27, B26, D28, AL28, AN26, AN27, AL26, AN28, AK28, AN29, AL27, AL29, AK29, AL31, AN30, AL32, AN31, AM34, AN32, AN34, AN33, AN2, AN1, AN3, AM1, AN4, AL3, AN5, AL4, AL6, AK6, AL8, AN6, AK7, AN7, AL9, AN8, AN9, AL7
GND[1]	A1, A10, A13, A22, A25, A34, AB16, AB17, AB18, AB19, AB26, AB31, AB4, AB9, AC16, AC17, AC18, AC19, AD27, AE27, AE31, AE4, AE8, AF12, AF16, AF19, AF23, AG31, AH31, AH4, AJ14, AJ21, AK27, AK8, AL10, AL16, AL19, AL2, AL25, AL33, AP1, AP10, AP13, AP22, AP25, AP34, D10, D16, D19, D2, D25, D33, E27, E8, F14, F21, G31, G4, J12, J16, J19, J23, K27, K31, K4, K8, M16, M17, M18, M19, N16, N17, N18, N19, N26, N31, N4, N9, R16, R17, R18, R19, T12, T13, T15, T16, T17, T18, T19, T20, T22, T23, T26, T31, T4, T9, U12, U13, U15, U16, U17, U18, U19, U20, U22, U23, V12, V13, V15, V16, V17, V18, V19, V20, V22, V23, W12, W13, W15, W16, W17, W18, W19, W20, W22, W23, W26, W31, W4, W9, Y16, Y17, Y18, Y19
NC[2]	**LFE2M70:** H2, H1, G5, G6, M9, M10, H3, H4, P3, P4, P9, M7, P1, P2, N7, P7, AC7, AC5, AC6, AD5, AD4, AD3, AD10, AD8, AD2, AD1, AD9, AC11, AD6, AD7, AE1, AE2, AJ12, AH12, AL13, AK13, AE14, AG13, AH22, AH21, AG22, AG21, AF33, AF34, AC27, AC28, AD29, AD30, AE33, AE34, AD32, AD31, AB25, AC25, AB28, AA26, AD33, AD34, P30, P29, P31, P32, R25, T24, N34, N33, F24, G23, J22, G22, H21, K21, L19, L20, L18, K19, J14, L15, H14, K14, F12, D11, F11, E11, A11, A12, A23, A24, AA11, AB11, AC26, AC30, AD11, AD12, AD13, AD14, AD15, AD19, AD21, AD22, AD23, AE10, AE11, AE12, AE13, AE19, AE21, AE22, AE23, AF11, AF21, AF22, AF24, AF8, AF9, AG10, AG11, AG24, AG25, AG26, AG3, AG7, AG8, AG9, AH10, AH11, AH13, AH24, AH25, AH26, AH27, AH5, AH6, AH7, AH8, AH9, AJ10, AJ11, AJ13, AJ24, AJ25, AJ26, AJ27, AJ3, AJ4, AJ5, AJ6, AJ7, AJ8, AJ9, AK10, AK11, AK12, AK24, AK25, AK26, AK4, AK9, AL11, AL12, AL34, AM10, AM11, AM13, AM25, AN10, AN11, AN12, AN13, AN24, AN25, AP11, AP12, AP24, B10, B11, B12, B13, B22, B23, B24, B25, C10, C11, C13, C22, C24, C25, D1, D15, D24, D34, E10, E24, E25, E26, E3, E31, E32, E33, E34, E4, E9, F10, F25, F26, F27, F28, F29, F30, F31, F32, F33, F34, F5, F6, F7, F8, F9, G10, G11, G24, G25, G26, G27, G28, G29, G30, G33, G34, G7, G8, G9, H10, H11, H24, H25, H26, H27, H28, H29, H8, H9, J10, J11, J24, J25, J26, J9, K10, K11, K12, K13, K23, K24, K25, K26, L11, L12, L13, L14, L21, L22, L23, L24, L25, L26, M11, M24, M25, M6, M8, N10, N11, P10, P25, P26, R9, T11, U11, W11, Y10, Y11 **LFE2M100:** A11, A12, A23, A24, AA11, AB11, AC26, AC30, AD11, AD12, AD13, AD14, AD15, AD19, AD21, AD22, AD23, AE10, AE11, AE12, AE13, AE19, AE21, AE22, AE23, AF11, AF21, AF22, AF24, AF8, AF9, AG10, AG11, AG24, AG25, AG26, AG3, AG7, AG8, AG9, AH10, AH11, AH13, AH24, AH25, AH26, AH27, AH5, AH6, AH7, AH8, AH9, AJ10, AJ11, AJ13, AJ24, AJ25, AJ26, AJ27, AJ3, AJ4, AJ5, AJ6, AJ7, AJ8, AJ9, AK10, AK11, AK12, AK24, AK25, AK26, AK4, AK9, AL11, AL12, AL34, AM10, AM11, AM13, AM25, AN10, AN11, AN12, AN13, AN24, AN25, AP11, AP12, AP24, B10, B11, B12, B13, B22, B23, B24, B25, C10, C11, C13, C22, C24, C25, D1, D15, D24, D34, E10, E24, E25, E26, E3, E31, E32, E33, E34, E4, E9, F10, F25, F26, F27, F28, F29, F30, F31, F32, F33, F34, F5, F6, F7, F8, F9, G10, G11,G24, G25, G26, G27, G28, G29, G30, G33, G34, G7, G8, G9, H10, H11, H24, H25, H26, H27, H28, H29, H8, H9, J10, J11, J24, J25, J26, J9, K10, K11, K12, K13, K23, K24, K25, K26, L11, L12, L13, L14, L21, L22, L23, L24, L25, L26, M11, M24, M25, M6, M8, N10, N11, P10, P25, P26, R9, T11, U11, W11, Y10, Y11

1. All grounds must be electrically connected at the board level. For fpBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
2. NC pins should not be connected to any active signals, VCC or GND.
3. For package migration across device densities, the designer must comprehend the package pin requirements for the SERDES blocks. Specifically, the SERDES power pins of the largest density device must be accounted to accommodate migration to other smaller devices using the same package. Please refer to TN1160, LatticeECP2/M Density Migration for more details.

LFE2-20E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-20E/SE					
Ball Number	Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
P5	P5	VCCIO5	5		
K5	K5	VCCIO6	6		
M3	M3	VCCIO6	6		
E3	E3	VCCIO7	7		
G5	G5	VCCIO7	7		
T15	T15	VCCIO8	8		
A1	A1	GND	-		
A16	A16	GND	-		
B12	B12	GND	-		
B5	B5	GND	-		
C8	C8	GND	-		
E15	E15	GND	-		
E2	E2	GND	-		
H14	H14	GND	-		
H8	H8	GND	-		
H9	H9	GND	-		
J3	J3	GND	-		
J8	J8	GND	-		
J9	J9	GND	-		
M15	M15	GND	-		
M2	M2	GND	-		
P9	P9	GND	-		
R12	R12	GND	-		
R5	R5	GND	-		
T1	T1	GND	-		
T16	T16	GND	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
U24	PR30B	3	RLM0_GPLLC_IN_A**/RDQ34	C (LVDS)*	PR44B	3	RLM0_GPLLC_IN_A**/RDQ48	C (LVDS)*
U25	PR30A	3	RLM0_GPLLT_IN_A**/RDQ34	T (LVDS)*	PR44A	3	RLM0_GPLLT_IN_A**/RDQ48	T (LVDS)*
R20	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
P18	VCC	3			VCCPLL	3		
T19	PR28B	3	RLM0_GDLLC_FB_A/RDQ25	C	PR42B	3	RLM0_GDLLC_FB_A/RDQ39	C
U20	PR28A	3	RLM0_GDLLT_FB_A/RDQ25	T	PR42A	3	RLM0_GDLLT_FB_A/RDQ39	T
GND	GNDIO3	-			GNDIO3	-		
T25	PR27B	3	RLM0_GDLLC_IN_A**/RDQ25	C (LVDS)*	PR41B	3	RLM0_GDLLC_IN_A**/RDQ39	C (LVDS)*
T26	PR27A	3	RLM0_GDLLT_IN_A**/RDQ25	T (LVDS)*	PR41A	3	RLM0_GDLLT_IN_A**/RDQ39	T (LVDS)*
T20	PR26B	3	RDQ25	C	PR40B	3	RDQ39	C
T22	PR26A	3	RDQ25	T	PR40A	3	RDQ39	T
VCCIO	VCCIO3	3			VCCIO3	3		
R26	PR25B	3	RDQ25	C (LVDS)*	PR39B	3	RDQ39	C (LVDS)*
R25	PR25A	3	RDQS25***	T (LVDS)*	PR39A	3	RDQS39***	T (LVDS)*
R22	NC	-			PR38B	3	RDQ39	C
GND	GNDIO3	-			GNDIO3	-		
T21	NC	-			PR38A	3	RDQ39	T
P26	NC	-			NC	-		
P25	NC	-			NC	-		
R24	NC	-			NC	-		
VCCIO	VCCIO3	3			VCCIO3	3		
R23	NC	-			NC	-		
P20	NC	-			NC	-		
R19	NC	-			NC	-		
P21	NC	-			PR34B	3	RDQ31	C
GND	GNDIO3	-			GNDIO3	-		
P19	NC	-			PR34A	3	RDQ31	T
P23	NC	-			PR33B	3	RDQ31	C (LVDS)*
P22	NC	-			PR33A	3	RDQ31	T (LVDS)*
N22	NC	-			PR32B	3	RDQ31	C
VCCIO	VCCIO3	3			VCCIO3	3		
R21	NC	-			PR32A	3	RDQ31	T
N26	NC	-			PR31B	3	RDQ31	C (LVDS)*
N25	NC	-			PR31A	3	RDQS31	T (LVDS)*
GND	GNDIO3	-			GNDIO3	-		
N19	PR24B	3	RDQ25	C	PR30B	3	RDQ31	C
N20	PR24A	3	RDQ25	T	PR30A	3	RDQ31	T
M26	PR23B	3	RDQ25	C (LVDS)*	PR29B	3	RDQ31	C (LVDS)*
M25	PR23A	3	RDQ25	T (LVDS)*	PR29A	3	RDQ31	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO3	3		
N18	PR22B	3	VREF2_3/RDQ25	C	PR28B	3	VREF2_3/RDQ31	C
N21	PR22A	3	VREF1_3/RDQ25	T	PR28A	3	VREF1_3/RDQ31	T
L26	PR21B	3	PCLKC3_0/RDQ25	C (LVDS)*	PR27B	3	PCLKC3_0/RDQ31	C (LVDS)*
L25	PR21A	3	PCLKT3_0/RDQ25	T (LVDS)*	PR27A	3	PCLKT3_0/RDQ31	T (LVDS)*
N24	PR19B	2	PCLKC2_0/RDQ16	C	PR25B	2	PCLKC2_0/RDQ22	C
M23	PR19A	2	PCLKT2_0/RDQ16	T	PR25A	2	PCLKT2_0/RDQ22	T

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
L2	PL24B	7	LDQ24	C (LVDS)*	PL37B	7	LDQ37	C (LVDS)*
L1	PL25A	7	LUM0_SPLLT_IN_A/LDQ24	T	PL38A	7	LUM0_SPLLT_IN_A/LDQ37	T
VCCIO	VCCIO7	7			VCCIO7	7		
M2	PL25B	7	LUM0_SPLLC_IN_A/LDQ24	C	PL38B	7	LUM0_SPLLC_IN_A/LDQ37	C
M1	PL26A	7	LUM0_SPLLT_FB_A/LDQ24	T	PL39A	7	LUM0_SPLLT_FB_A/LDQ37	T
N2	PL26B	7	LUM0_SPLLC_FB_A/LDQ24	C	PL39B	7	LUM0_SPLLC_FB_A/LDQ37	C
GND	GNDIO7	-			GNDIO7	-		
M8	VCCPLL	7			NC	-		
VCCIO	VCCIO7	7			VCCIO7	7		
GND	GNDIO7	-			GNDIO7	-		
N1	PL37A	7	LDQ41		PL50A	7	LDQ54	
L8	PL38A	7	LDQ41	T	PL51A	7	LDQ54	T
K8	PL38B	7	LDQ41	C	PL51B	7	LDQ54	C
VCCIO	VCCIO7	7			VCCIO7	7		
L6	PL39A	7	LDQ41	T (LVDS)*	PL52A	7	LDQ54	T (LVDS)*
K5	PL39B	7	LDQ41	C (LVDS)*	PL52B	7	LDQ54	C (LVDS)*
L7	PL40A	7	LDQ41	T	PL53A	7	LDQ54	T
L5	PL40B	7	LDQ41	C	PL53B	7	LDQ54	C
GND	GNDIO7	-			GNDIO7	-		
P1	PL41A	7	LDQS41	T (LVDS)*	PL54A	7	LDQS54	T (LVDS)*
P2	PL41B	7	LDQ41	C (LVDS)*	PL54B	7	LDQ54	C (LVDS)*
M6	PL42A	7	LDQ41	T	PL55A	7	LDQ54	T
VCCIO	VCCIO7	7			VCCIO7	7		
N8	PL42B	7	LDQ41	C	PL55B	7	LDQ54	C
R1	PL43A	7	LDQ41	T (LVDS)*	PL56A	7	LDQ54	T (LVDS)*
R2	PL43B	7	LDQ41	C (LVDS)*	PL56B	7	LDQ54	C (LVDS)*
M7	PL44A	7	PCLKT7_0/LDQ41	T	PL57A	7	PCLKT7_0/LDQ54	T
GND	GNDIO7	-			GNDIO7	-		
N9	PL44B	7	PCLKC7_0/LDQ41	C	PL57B	7	PCLKC7_0/LDQ54	C
M4	PL46A	6	PCLKT6_0/LDQ50	T (LVDS)*	PL59A	6	PCLKT6_0/LDQ63	T (LVDS)*
M5	PL46B	6	PCLKC6_0/LDQ50	C (LVDS)*	PL59B	6	PCLKC6_0/LDQ63	C (LVDS)*
N7	PL47A	6	VREF2_6/LDQ50	T	PL60A	6	VREF2_6/LDQ63	T
P9	PL47B	6	VREF1_6/LDQ50	C	PL60B	6	VREF1_6/LDQ63	C
N3	PL48A	6	LDQ50	T (LVDS)*	PL61A	6	LDQ63	T (LVDS)*
VCCIO	VCCIO6	6			VCCIO6	6		
N4	PL48B	6	LDQ50	C (LVDS)*	PL61B	6	LDQ63	C (LVDS)*
N5	PL49A	6	LDQ50	T	PL62A	6	LDQ63	T
P7	PL49B	6	LDQ50	C	PL62B	6	LDQ63	C
T1	PL50A	6	LDQS50	T (LVDS)*	PL63A	6	LDQS63	T (LVDS)*
GND	GNDIO6	-			GNDIO6	-		
T2	PL50B	6	LDQ50	C (LVDS)*	PL63B	6	LDQ63	C (LVDS)*
P8	PL51A	6	LDQ50	T	PL64A	6	LDQ63	T
P6	PL51B	6	LDQ50	C	PL64B	6	LDQ63	C
VCCIO	VCCIO6	6			VCCIO6	6		
P5	PL52A	6	LDQ50	T (LVDS)*	PL65A	6	LDQ63	T (LVDS)*
P4	PL52B	6	LDQ50	C (LVDS)*	PL65B	6	LDQ63	C (LVDS)*

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
W18	GND	-		
W19	GND	-		
Y14	GND	-		
Y15	GND	-		
Y16	GND	-		
Y17	GND	-		
A2	NC	-		
A3	NC	-		
A4	NC	-		
A5	NC	-		
AB28	NC	-		
AC4	NC	-		
AD23	NC	-		
AE1	NC	-		
AE2	NC	-		
AE29	NC	-		
AE3	NC	-		
AE30	NC	-		
AE4	NC	-		
AE5	NC	-		
AE6	NC	-		
AF1	NC	-		
AF2	NC	-		
AF23	NC	-		
AF26	NC	-		
AF27	NC	-		
AF28	NC	-		
AF29	NC	-		
AF3	NC	-		
AF30	NC	-		
AF4	NC	-		
AF5	NC	-		
AG1	NC	-		
AG13	NC	-		
AG16	NC	-		
AG18	NC	-		
AG2	NC	-		
AG26	NC	-		
AG27	NC	-		
AG28	NC	-		
AG29	NC	-		
AG3	NC	-		
AG30	NC	-		

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
U12	PB59B	4	BDQ60	C
GNDIO	GNDIO4	-		
AA12	PB60A	4	BDQS60	T
Y12	PB60B	4	BDQ60	C
V12	PB61A	4	BDQ60	T
W12	PB61B	4	BDQ60	C
AB12	PB62A	4	BDQ60	T
AA13	PB62B	4	BDQ60	C
VCCIO	VCCIO4	4		
T12	PB63A	4	BDQ60	T
U13	PB63B	4	BDQ60	C
V13	PB64A	4	BDQ60	T
T13	PB64B	4	BDQ60	C
GNDIO	GNDIO4	-		
AB13	PB65A	4	BDQ69	T
AB14	PB65B	4	BDQ69	C
U14	PB66A	4	BDQ69	T
T14	PB66B	4	BDQ69	C
AA14	PB67A	4	BDQ69	T
VCCIO	VCCIO4	4		
Y14	PB67B	4	BDQ69	C
W14	PB68A	4	BDQ69	T
V14	PB68B	4	BDQ69	C
AB15	PB69A	4	BDQS69	T
GNDIO	GNDIO4	-		
AA15	PB69B	4	BDQ69	C
V15	PB70A	4	BDQ69	T
U15	PB70B	4	BDQ69	C
AB16	PB71A	4	BDQ69	T
VCCIO	VCCIO4	4		
AA16	PB71B	4	BDQ69	C
AB17	PB72A	4	BDQ69	T
AA17	PB72B	4	BDQ69	C
GNDIO	GNDIO4	-		
W20	CFG2	8		
V20	CFG1	8		
V19	CFG0	8		
V22	PROGRAMN	8		
W22	CCLK	8		
U18	INITN	8		
U22	DONE	8		
GNDIO	GNDIO8	-		
U20	WRITEN***	8		

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
L11	GND	-		
L12	GND	-		
L13	GND	-		
M10	GND	-		
M11	GND	-		
M12	GND	-		
M13	GND	-		
N10	GND	-		
N11	GND	-		
N12	GND	-		
N13	GND	-		
N15	GND	-		
N20	GND	-		
N3	GND	-		
N8	GND	-		
P14	GND	-		
P9	GND	-		
R10	GND	-		
R13	GND	-		
T19	GND	-		
T4	GND	-		
W16	GND	-		
W2	GND	-		
W21	GND	-		
W7	GND	-		
Y10	GND	-		
Y13	GND	-		
Y15	NC	-		
W15	NC	-		
AB20	NC	-		
AB21	NC	-		
AA21	NC	-		
AA20	NC	-		
AB19	NC	-		
AB18	NC	-		
Y22	NC	-		
Y21	NC	-		
Y17	NC	-		
Y18	NC	-		
Y16	NC	-		
W17	NC	-		
Y19	NC	-		
Y20	NC	-		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA6	NC	-			PL79B	6	LDQ82	C
AB4	NC	-			PL80A	6	LDQ82	T (LVDS)*
-	-	-			VCCIO6	6		
AB5	NC	-			PL80B	6	LDQ82	C (LVDS)*
AA8	NC	-			PL81A	6	LDQ82	T
AA9	NC	-			PL81B	6	LDQ82	C
AC1	PL62A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	PL82A	6	LLM0_GPLLT_IN_A**/LDQS82	T (LVDS)*
GNDIO	GNDIO6	-			GNDIO6	-		
AC2	PL62B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	PL82B	6	LLM0_GPLLC_IN_A**/LDQ82	C (LVDS)*
AC4	PL63A	6	LLM0_GPLLT_FB_A	T	PL83A	6	LLM0_GPLLT_FB_A/LDQ82	T
AC3	PL63B	6	LLM0_GPLLC_FB_A	C	PL83B	6	LLM0_GPLLC_FB_A/LDQ82	C
VCCIO	VCCIO6	6			VCCIO6	6		
AC7	PL64A	6	LLM0_GDLLT_IN_A**	T (LVDS)*	PL84A	6	LLM0_GDLLT_IN_A**/LDQ82	T (LVDS)*
AC6	PL64B	6	LLM0_GDLLC_IN_A**	C (LVDS)*	PL84B	6	LLM0_GDLLC_IN_A**/LDQ82	C (LVDS)*
AC5	PL65A	6	LLM0_GDLLT_FB_A	T	PL85A	6	LLM0_GDLLT_FB_A/LDQ82	T
AD3	PL65B	6	LLM0_GDLLC_FB_A	C	PL85B	6	LLM0_GDLLC_FB_A/LDQ82	C
GNDIO	GNDIO6	-			GNDIO6	-		
AB8	LLM0_PLLCAP	6			LLM0_PLLCAP	6		
AD2	PL67A	6	LDQ71	T (LVDS)*	PL87A	6		T
AD1	PL67B	6	LDQ71	C (LVDS)*	PL87B	6		C
AE2	TCK	-			TCK	-		
AE1	TDI	-			TDI	-		
AF2	TMS	-			TMS	-		
AF1	TDO	-			TDO	-		
AG1	VCCJ	-			VCCJ	-		
AH1	VCC	-			LLC_SQ_VCCRX3	14		
AK2	PB11A	5	BDQ15	T	LLC_SQ_HDINP3	14		T
AJ1	NC	-			LLC_SQ_VCCIB3	14		
AJ2	PB11B	5	BDQ15	C	LLC_SQ_HDINN3	14		C
AH4	VCC	-			LLC_SQ_VCCTX3	14		
AK5	PB13A	5	BDQ15	T	LLC_SQ_HDOUTP3	14		T
AK4	NC	-			LLC_SQ_VCCOB3	14		
AJ5	PB13B	5	BDQ15	C	LLC_SQ_HDOUTN3	14		C
AH5	VCC	-			LLC_SQ_VCCTX2	14		
AJ6	PB14B	5	BDQ15	C	LLC_SQ_HDOUTN2	14		C
AH6	NC	-			LLC_SQ_VCCOB2	14		
AK6	PB14A	5	BDQ15	T	LLC_SQ_HDOUTP2	14		T
AH2	VCC	-			LLC_SQ_VCCRX2	14		
AJ3	PB12B	5	BDQ15	C	LLC_SQ_HDINN2	14		C
AH3	NC	-			LLC_SQ_VCCIB2	14		
AK3	PB12A	5	BDQ15	T	LLC_SQ_HDINP2	14		T
AH7	VCC	-			LLC_SQ_VCCP	14		
AG7	PB15A	5	BDQS15	T	LLC_SQ_REFCLKP	14		T
AF7	PB15B	5	BDQ15	C	LLC_SQ_REFCLKN	14		C
AJ7	VCCAUX	-			LLC_SQ_VCCAUX33	14		
AK11	PB18A	5	BDQ15	T	LLC_SQ_HDINP1	14		T
AH11	NC	-			LLC_SQ_VCCIB1	14		
AJ11	PB18B	5	BDQ15	C	LLC_SQ_HDINN1	14		C

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
M23	GND	-		
M8	GND	-		
N14	GND	-		
N15	GND	-		
N16	GND	-		
N17	GND	-		
N27	GND	-		
N4	GND	-		
P11	GND	-		
P13	GND	-		
P14	GND	-		
P15	GND	-		
P16	GND	-		
P17	GND	-		
P18	GND	-		
P20	GND	-		
R10	GND	-		
R11	GND	-		
R13	GND	-		
R14	GND	-		
R15	GND	-		
R16	GND	-		
R17	GND	-		
R18	GND	-		
R20	GND	-		
R21	GND	-		
R24	GND	-		
R7	GND	-		
T10	GND	-		
T11	GND	-		
T13	GND	-		
T14	GND	-		
T15	GND	-		
T16	GND	-		
T17	GND	-		
T18	GND	-		
T20	GND	-		
T21	GND	-		
T24	GND	-		
T7	GND	-		
U11	GND	-		
U13	GND	-		
U14	GND	-		

LatticeECP2M Part Number Description

LFE2M XXX XE – X XXXXXX X

Device Family
ECP2M (LatticeECP2 FPGA + SERDES)

Logic Capacity
20 = 20K LUTs
35 = 35K LUTs
50 = 50K LUTs
70 = 70K LUTs
100 = 100K LUTs

Encryption
S = Security Series (Encryption Feature)
Blank = Standard Series (No Encryption)

Supply Voltage
E = 1.2V

Grade
C = Commercial
I = Industrial

Package
F256 = 256-ball fpBGA
F484 = 484-ball fpBGA
F672 = 672-ball fpBGA
F900 = 900-ball fpBGA
F1152 = 1152-ball fpBGA

FN256 = 256-ball Lead-free fpBGA
FN484 = 484-ball Lead-free fpBGA
FN672 = 672-ball Lead-free fpBGA
FN900 = 900-ball Lead-free fpBGA
FN1152 = 1152-ball Lead-free fpBGA

Speed
5 = Slowest
6
7 = Fastest

Ordering Information

Note:þLatticeECP2M devices are dual marked. For example, the commercial speed grade LFE2M50E-7F672C is also marked with industrial grade -6I (LFE2M50E-6F672I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial grade does not have industrial markings. The markings appear as follows:

LatticeECP2/M Family Data Sheet Supplemental Information

July 2012 **Data Sheet DS1006**

For Further Information

A variety of technical notes for the LatticeECP2/M family are available on the Lattice web site at www.latticesemi.com.

- TN1102, LatticeECP2/M sysIO Usage Guide
- TN1103, LatticeECP2/M sysCLOCK PLL Design and Usage Guide
- TN1104, LatticeECP2/M Memory Usage Guide
- TN1105, LatticeECP2/M High-Speed I/O Interface
- TN1106, Power Estimation and Management for LatticeECP2/M Devices
- TN1107, LatticeECP2/M sysDSP Usage Guide
- TN1108, LatticeECP2/M sysCONFIG Usage Guide
- TN1109, LatticeECP2/M Configuration Encryption Usage Guide
- TN1113, LatticeECP2/M Soft Error Detection (SED) Usage Guide
- TN1124, LatticeECP2M SERDES/PCS Usage Guide
- TN1162, LatticeECP2/M Hardware Checklist

For further information about interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: www.pcisig.com